1. Shock & Drop • Vibration
Do not inflict excessive shock and mechanical vibration that exceeds the norm, such as hitting or mistakenly dropping, when transporting and mounting on a board. There are cases when pieces of crystal break, and pieces that are used become damaged, and become inoperable. When a shock or vibration that exceeds the norm has been inflicted, make sure to check the characteristics.

2. Cleaning
Since a crystal piece can be broken by resonance when a crystal device is cleaned by ultrasonic cleaning, be careful when carrying out ultrasonic cleaning.

3. Soldering conditions
To maintain the product reliability, please follow recommended conditions.

**Standard soldering iron conditions**

<table>
<thead>
<tr>
<th>Soldering iron</th>
<th>Crystal Units</th>
</tr>
</thead>
<tbody>
<tr>
<td>280°C to 340°C</td>
<td></td>
</tr>
</tbody>
</table>

**Reflow conditions (Example)**

```
Temperature (°C) 200°C min. 30 to 45 sec. 260°C max. 10 sec`

Ramp-Up 1 to 3°C/sec

Cool Down 2.5 to 5°C/sec

Hold-Time 1 to 2 min.
```

Recommended reflow Conditions vary depending upon products. Please check with the respective specification for details.

4. Mounting Precautions
The lead of the device and the pattern of the board is soldered on the surface. Since extreme deformation of the board tears off the pattern, tears off the lead metal, cracks the solder and damages the sealed part of the device and there are cases in which performance deteriorates and operation fails, use it within the stipulated bending conditions. Due to the small cracks in the board resulting from mounting, please pay sufficient attention when attaching a device at the position where the warping of the board is great.

When using an automatic loading machine, as far as possible, select a type that has a small impact and use it while confirming that there is no damage.

Surface mount devices are NOT flow soldering compatible.

5. Storage Condition
Since the long hour high temperature and low temperature storage, as well as the storage at high humidity are causes of deterioration in frequency accuracy and solderability.

Parts should be stored in temperature range of −5 to +40°C, humidity 40 to 60% RH, and avoid direct sunlight. Then use within 6 months.